# ECAL activities WP9.5

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Develop a high granularity electromagnetic calorimeter for use in combined test beams

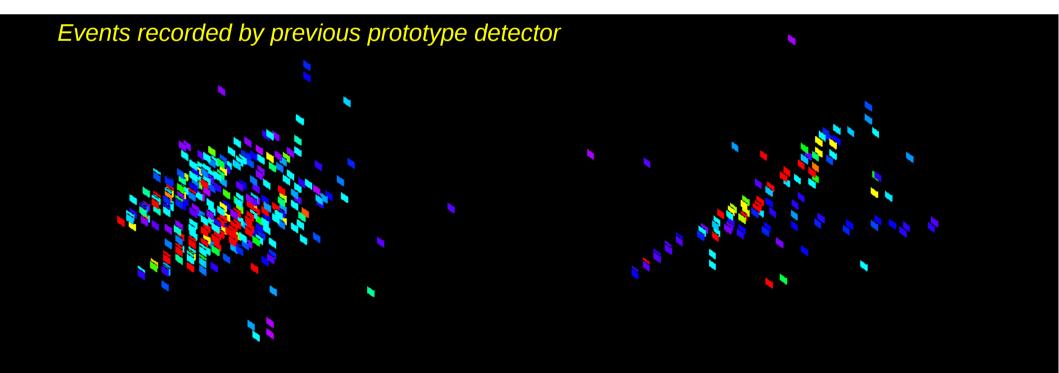
Milestone (M36):

Provide an electromagnetic calorimeter extended from the EUDET model

# ECAL design concept

Sampling calorimeter with tungsten absorber and highly segmented silicon readout planes

Gives an ECAL with Imaging capabilities *(e.g. interaction point)* 2-particle separation, reasonable EM energy resolution

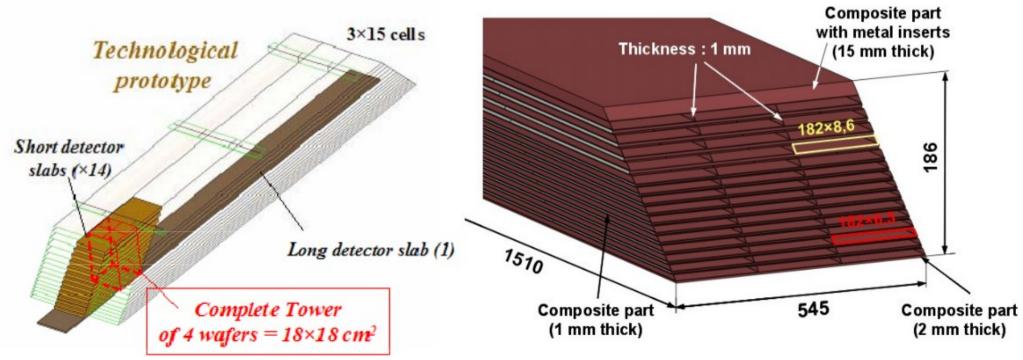


# ECAL design

Mechanical support structure integrating absorber layers carbon fibre composite material

18x18cm2 tower instrumented with silicon sensors 5X5mm2 readout granularity finer longitudinal sampling in first detector section

Reaout by CALICE DAQ"2" system and eventually common DAQ from AIDA 8.6.2



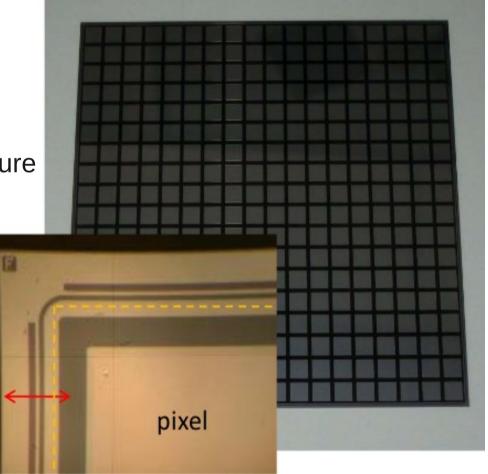
#### Silicon sensors

Matrix of 5x5mm2 PIN diodes sensor size typically 9x9cm2

High resistivity silicon (~5 k $\Omega$ ·cm) fully depleted by ~100V reverse bias

Around 150 of such sensors required >50 have been purchased

R&D continuing on sensor design: reduced/modified guard ring (GR) structure (introduced dead space, GR-pixel xtalk) design simplification with aim to reduced unit price



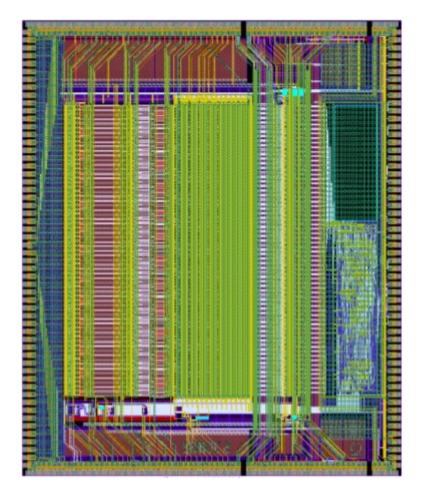
#### Reaout ASIC

SKIROC2, developed by Omega 35um SiGe, 7.1x8.5mm2

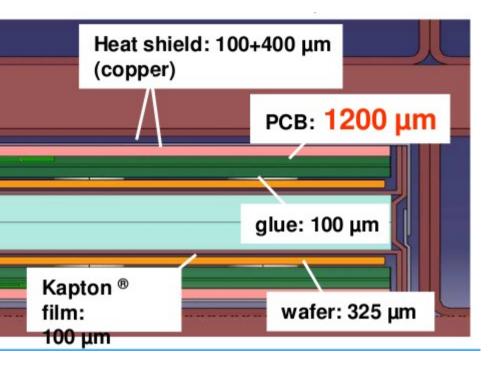
64 channels / ASIC Variable gain charge-sensitive pre-amp Dual-gain shaper, also fast shaper for trigger 15-depth memory 12-bit Wilkinson ADC

Low power design (~1.5 mW/channel)

Produced, functionality tested



#### PCB, detector integration



Compact connections used to connect ASUs and adapter card (for power, DAQ connections)

ASU placed onto mechanical support (carbon fibre composite) inserted into mechanical structure Sensors and ASICs mounted on PCBs 18X18cm2, ~1mm thick "Active Sensor Unit" ASU

Sensor mounted with dots of conductive glue

At present using packaged ASICs mounted on PCB surface

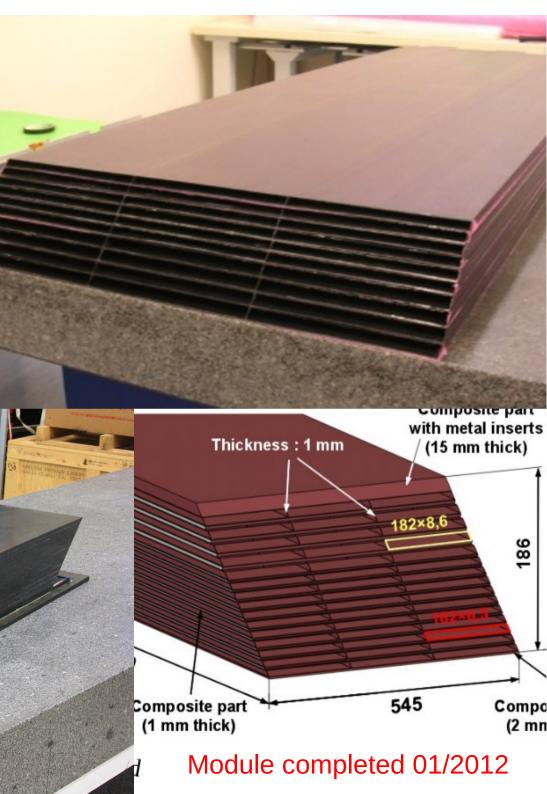
Eventually encapsulate unpackaged ASIC into PCB thickness



#### Mechanical structure

~1.5m long, ~0.5m wide, ~0.2m thick

Modular construction 15 alveola, cut to size (2 thicknesses) then assembles and cured with W plates



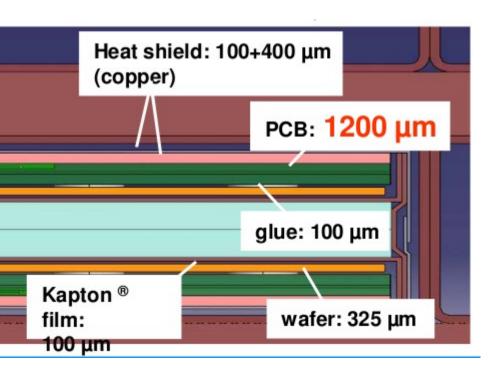
### Cooling

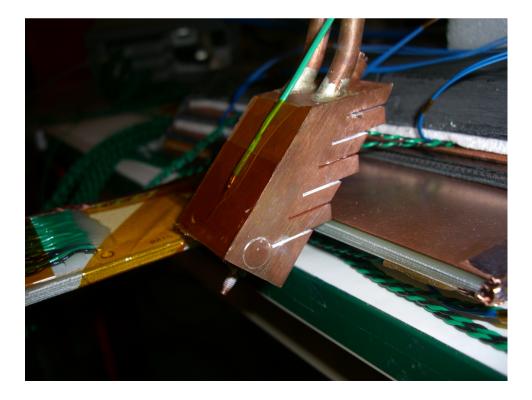
Evacuate heat produced by ASICs

Passive copper layer in contact with ASUs inside structure

Water-cooled heat exchanger at end of module

System designed, constructed and tested





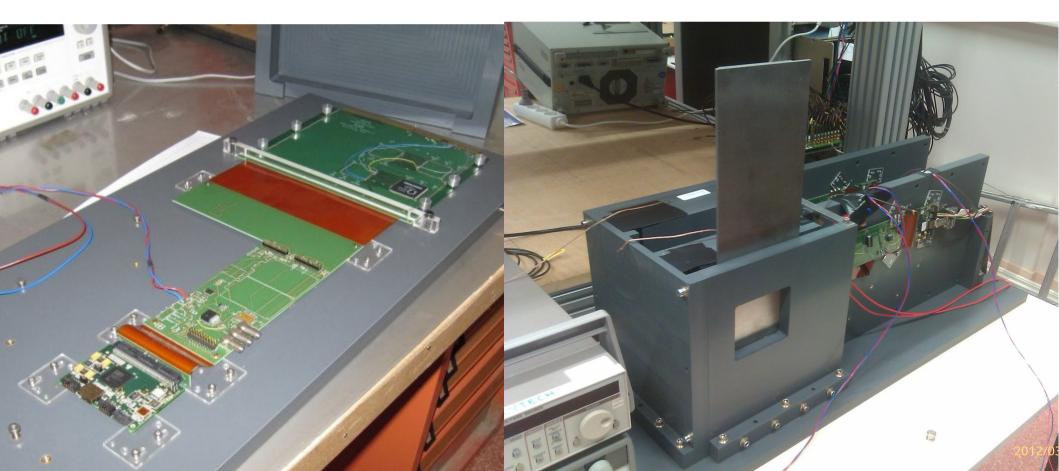


#### System commissioning

A few test ASUs have been produced (reduced channels, sensitive area)

tested in the lab, currently being beam-tested at DESY (H24 beam line) with efirst signs are encouraging...

Larger-scale tests (~10 layers) planned for 07/2012



### Summary

Developing high granularity ECAL for test beams

All elements more-or-less completed (some in reduced/prototype form)

Small-scale system tests are now underway Debugging, improvements, ....

Do not forsee major problems to achieve milestone (Month 36, ~2 years from today)